

## Hyper Speed Control<sup>®</sup> 3A Buck Regulator

### Features

- Input Voltage: 2.7V to 5.5V
- 3A Output Current
- Up To 95% Efficiency
- Up To 3.3 MHz Operation
- Safe Start-Up into a Pre-Biased Output
- Power Good Output
- Ultra-Fast Transient Response
- Low Output Voltage Ripple
- Low  $R_{DS(ON)}$  Integrated MOSFET Switches
- 0.01  $\mu$ A Shutdown Current
- Thermal Shutdown and Current Limit Protection
- Output Voltage as low as 0.7V
- 3 mm  $\times$  4 mm DFN-10L
- $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$  Junction Temperature Range

### Applications

- DTVs
- Set-Top Boxes
- Printers
- DVD Players
- Distributed Power Supplies

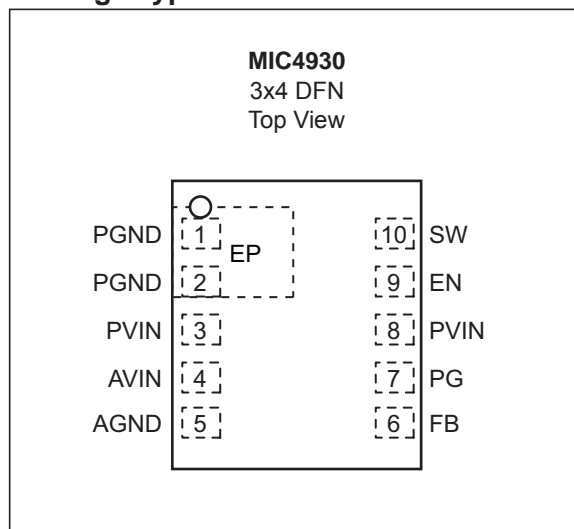
### General Description

The MIC4930 is a high-efficiency, 3A synchronous buck regulator with ultra-fast transient response perfectly suited for supplying processor core and I/O voltages from a 5V or 3.3V bus. The MIC4930 provides a switching frequency up to 3.3 MHz while achieving peak efficiencies up to 95%. An additional benefit of high-frequency operation is very low output ripple voltage throughout the entire load range with the use of a small output capacitor. The MIC4930 is designed for use with a very small inductor, down to 1  $\mu$ H, and an output ceramic capacitor as small as 10  $\mu$ F without the need for external ripple injection. A wide range of output capacitor types and values can also be accommodated.

The MIC4930 supports safe start-up into a pre-biased output.

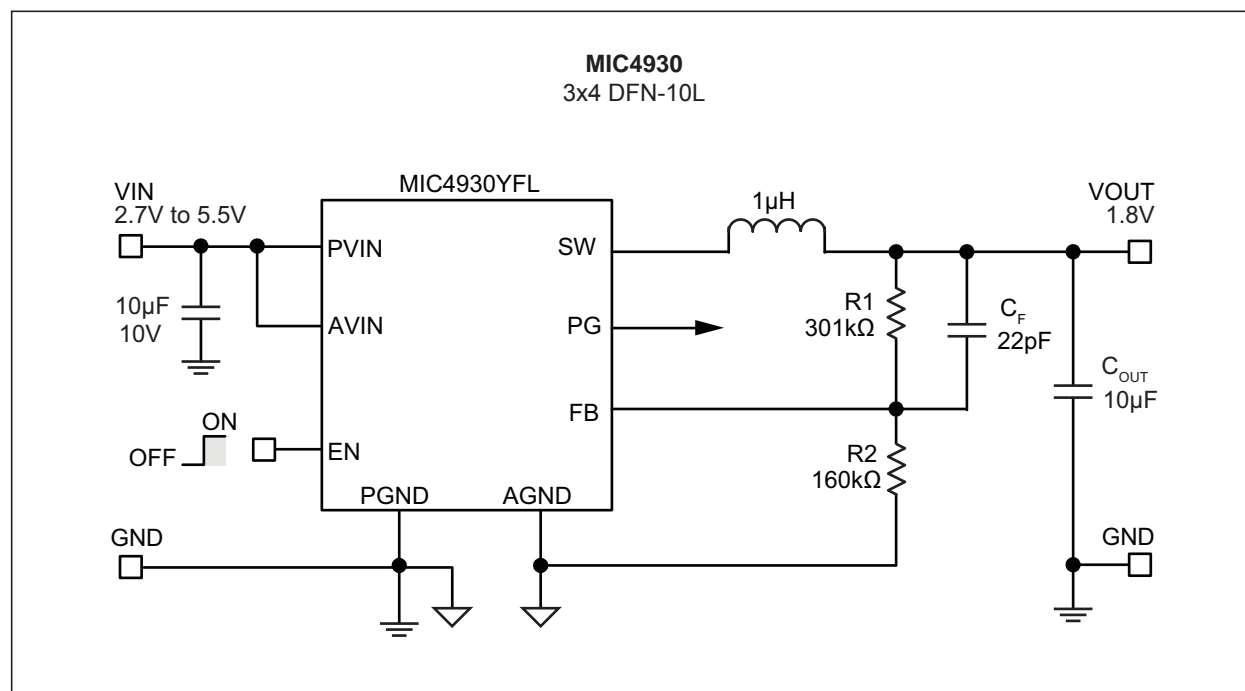
The MIC4930 is available in a 10-pin 3 mm  $\times$  4 mm DFN package with an operating junction temperature range from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . The MIC4930 is pin-to-pin compatible with the 5A-rated MIC4950YFL.

### Package Type



# MIC4930

## Typical Application Circuit



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

PV <sub>IN</sub> , AV <sub>IN</sub> Supply Voltage (V <sub>IN</sub> ).....	–0.3V to +6V
SW Output Switch Voltage (V <sub>SW</sub> ).....	–0.3V to V <sub>IN</sub>
EN, PG (V <sub>EN</sub> , V <sub>PG</sub> ).....	–0.3V to V <sub>IN</sub>
FB Feedback Input Voltage (V <sub>FB</sub> ) .....	–0.3V to V <sub>IN</sub>
ESD Protection On All Pins (Note 1).....	±2 kV HBM

### Operating Ratings ††

Supply Voltage (V <sub>IN</sub> ) .....	+2.7V to +5.5V
Enable Input Voltage (V <sub>EN</sub> ) .....	0V to V <sub>IN</sub>

† **Notice:** Exceeding the absolute maximum ratings may damage the device.

†† **Notice:** The device is not guaranteed to function outside its operating ratings.

**Note 1:** Devices are ESD sensitive. Handling precautions are recommended. Human body model, 1.5 kΩ in series with 100 pF.

### ELECTRICAL CHARACTERISTICS (Note 1)

<b>Electrical Characteristics:</b> Unless otherwise indicated, V <sub>IN</sub> = V <sub>EN</sub> = 3.3V; L = 1.0 μH; T <sub>A</sub> = 25°C, C <sub>IN</sub> = 10 μH, C <sub>OUT</sub> = 10 μH.						
Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Supply Voltage Range	V <sub>IN</sub>	<b>2.7</b>	—	<b>5.5</b>	V	—
Undervoltage lockout threshold	V <sub>UVLO</sub>	<b>2.41</b>	2.5	<b>2.61</b>	V	(turn-on)
Undervoltage lockout hysteresis	V <sub>UVLOH</sub>	—	400	—	mV	—
Quiescent current	I <sub>Q</sub>	—	0.8	<b>2</b>	mA	I <sub>OUT</sub> = 0 mA, FB > 1.2 × V <sub>FB(Nominal)</sub>
Shutdown current	I <sub>SD</sub>	—	0.01	<b>2</b>	μA	V <sub>EN</sub> = 0V
Feedback voltage	V <sub>FB</sub>	<b>0.609</b>	0.625	<b>0.640</b>	V	—
Current limit	I <sub>LIMIT</sub>	3.5	5.75	8	A	FB = 0.9V × V <sub>FB(Nominal)</sub>
Output voltage line regulation	LINEREG	—	1	—	%V	V <sub>IN</sub> = 2.7V to 3.5V, V <sub>OUTNOM</sub> = 1.8V, I <sub>LOAD</sub> = 20 mA
						V <sub>IN</sub> = 4.5V to 5.5V if V <sub>OUTNOM</sub> ≥ 2.5V, I <sub>LOAD</sub> = 20 mA

**Note 1:** Specification for packaged product only.

## ELECTRICAL CHARACTERISTICS (CONTINUED)(Note 1)

Electrical Characteristics: Unless otherwise indicated, $V_{IN} = V_{EN} = 3.3V$ ; $L = 1.0 \mu H$ ; $T_A = 25^\circ C$ , $C_{IN} = 10 \mu H$ , $C_{OUT} = 10 \mu H$ .						
Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Output voltage load regulation	LOADREG	—	0.3	—	%	$20 \text{ mA} < I_{LOAD} < 500 \text{ mA}$ , $V_{IN} = 3.6V$ if $V_{OUTNOM} < 2.5V$
						$20 \text{ mA} < I_{LOAD} < 500 \text{ mA}$ , $V_{IN} = 5.0V$ if $V_{OUTNOM} \geq 2.5V$
		—	1	—	%	$20 \text{ mA} < I_{LOAD} < 3A$ , $V_{IN} = 3.6V$ if $V_{OUTNOM} < 2.5V$
						$20 \text{ mA} < I_{LOAD} < 3 \text{ mA}$ , $V_{IN} = 5.0V$ if $V_{OUTNOM} \geq 2.5V$
PWM switch ON resistance	$R_{DS(on)-P}$	—	30	—	m $\Omega$	$I_{SW} = 1A$ P-Channel MOSFET
	$R_{DS(on)-N}$	—	25	—		$I_{SW} = 1A$ N-Channel MOSFET
Maximum turn-on time	$t_{ON}$	—	665	—	ns	$V_{IN} = 4.5V$ , $V_{FB} = 0.5V$
		—	1000	—		$V_{IN} = 3.0V$ , $V_{FB} = 0.5V$
		—	1120	—		$V_{IN} = 2.7V$ , $V_{FB} = 0.5V$
Minimum turn-off time	$t_{OFF}$	—	176	—	ns	$V_{IN} = 3.0V$ , $V_{FB} = 0.5V$
Soft-start time	$t_{SOFT-ON}$	—	500	—	$\mu s$	$V_{OUT} = 90\%$ of $V_{OUTNOM}$
Enable threshold	$V_{EN}$	<b>0.5</b>	0.8	<b>1.2</b>	V	Turn-on
Enable input current	$I_{EN}$		0.1	<b>1</b>	$\mu A$	—
Power Good threshold	$V_{OUTPG}$	<b>82</b>	88	<b>94</b>	%	Rising
Power Good hysteresis	$V_{OUTPGH}$	—	7	—	%	—
Overtemperature shutdown	$T_{SD}$		150		$^\circ C$	—
Overtemperature shutdown hysteresis	$T_{SDH}$		20		$^\circ C$	—

**Note 1:** Specification for packaged product only.

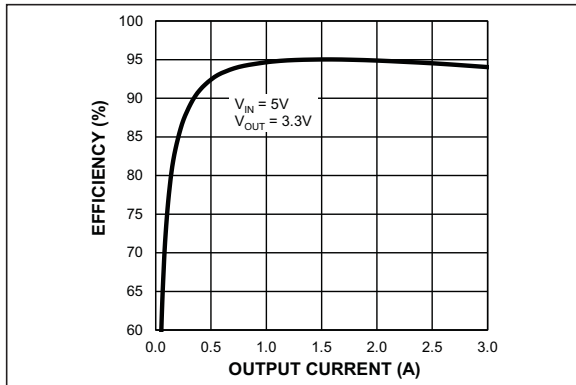
## TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
<b>Temperature Ranges</b>						
Storage Temperature	$T_S$	-65	—	+150	°C	—
Junction Operating Temperature	$T_J$	-40	—	+125	°C	—
<b>Package Thermal Resistances</b>						
Thermal Resistance, DFN-10Ld	$\theta_{JA}$	—	35	—	°C/W	—

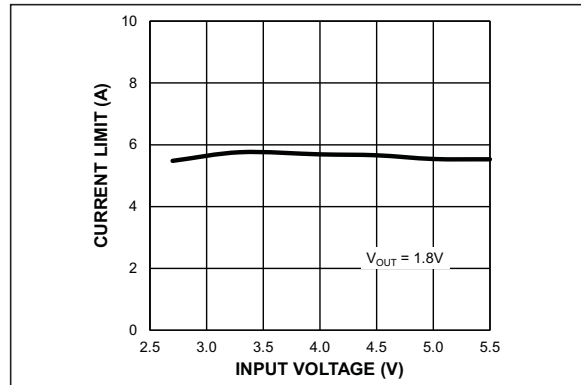
**Note 1:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air (i.e.,  $T_A$ ,  $T_J$ ,  $\theta_{JA}$ ). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

## 2.0 TYPICAL PERFORMANCE CURVES

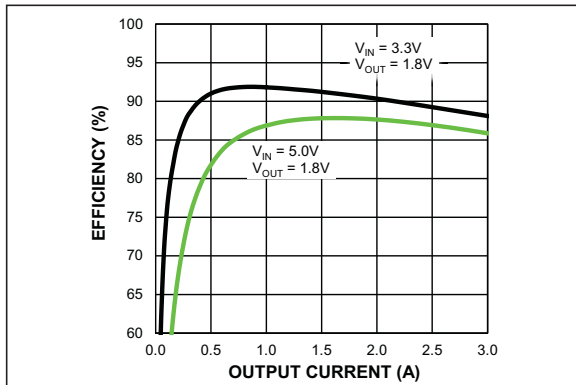
**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.



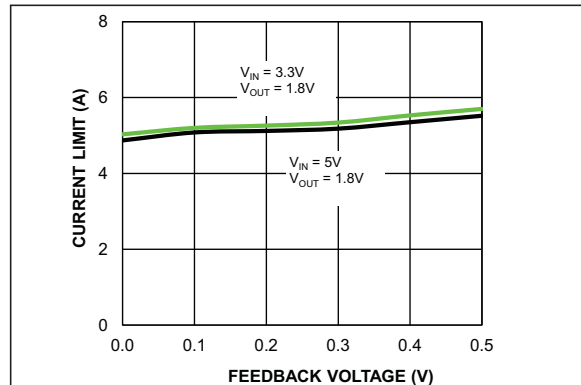
**FIGURE 2-1:** Efficiency vs. Output Current.



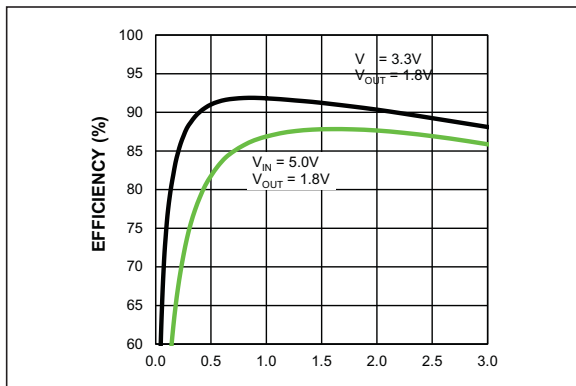
**FIGURE 2-4:** Current Limit vs. Input Voltage.



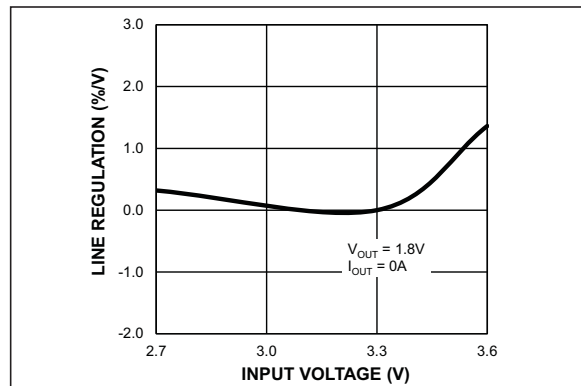
**FIGURE 2-2:** Efficiency vs. Output Current.



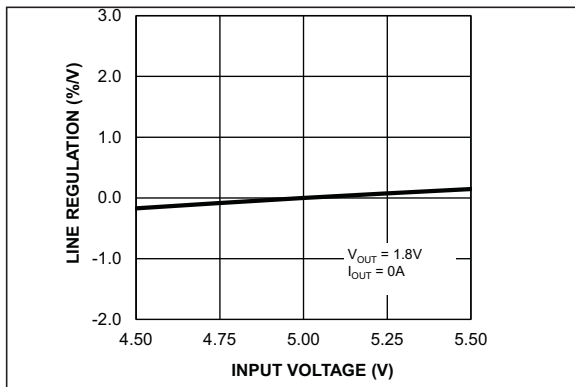
**FIGURE 2-5:** Current Limit vs. Feedback Voltage.



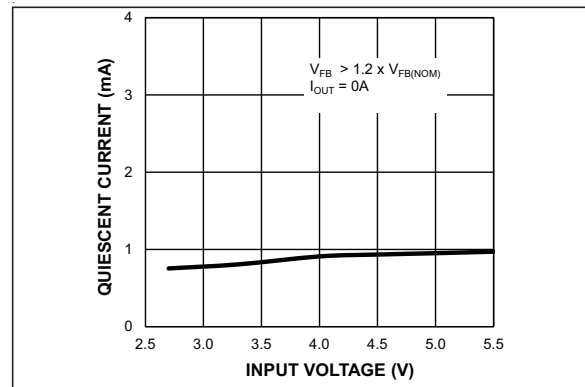
**FIGURE 2-3:** Efficiency vs. Output Current.



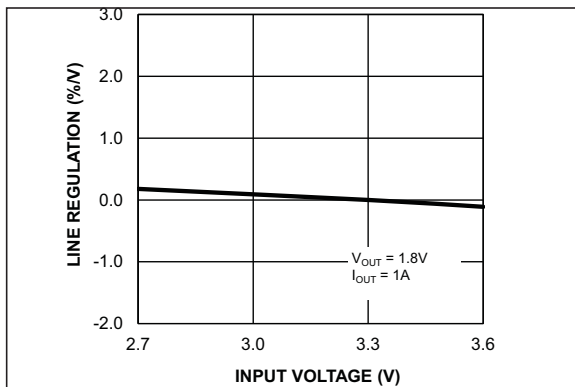
**FIGURE 2-6:** Line Regulation vs. Input Voltage.



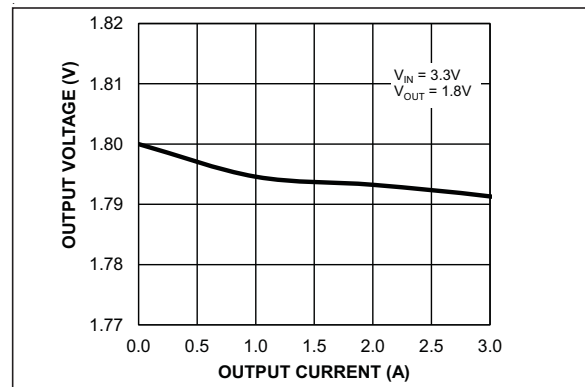
**FIGURE 2-7:** Line Regulation vs. Input Voltage.



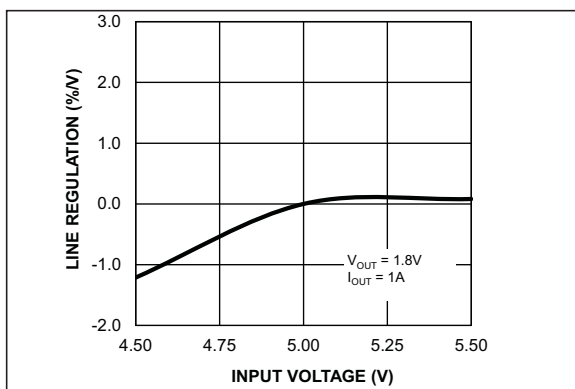
**FIGURE 2-10:** Quiescent Current vs. Input Voltage.



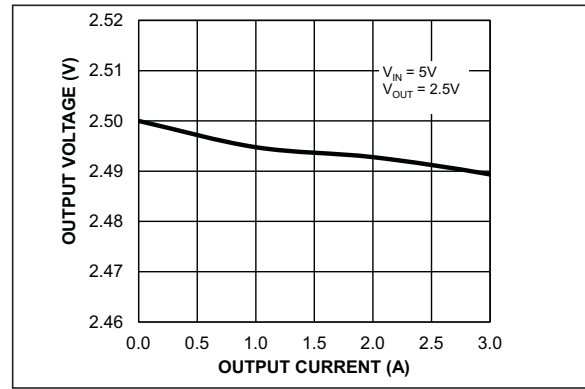
**FIGURE 2-8:** Line Regulation vs. Input Voltage.



**FIGURE 2-11:** Output Voltage ( $V_{IN} = 3.3V$ ) vs. Output Current.



**FIGURE 2-9:** Line Regulation vs. Input Voltage.



**FIGURE 2-12:** Output Voltage ( $V_{IN} = 5V$ ) vs. Output Current.

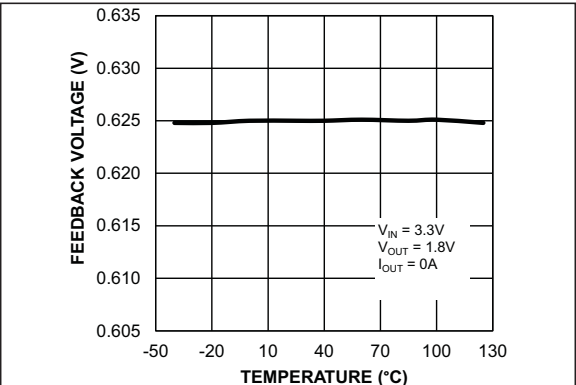


FIGURE 2-13: Feedback Voltage vs. Temperature.

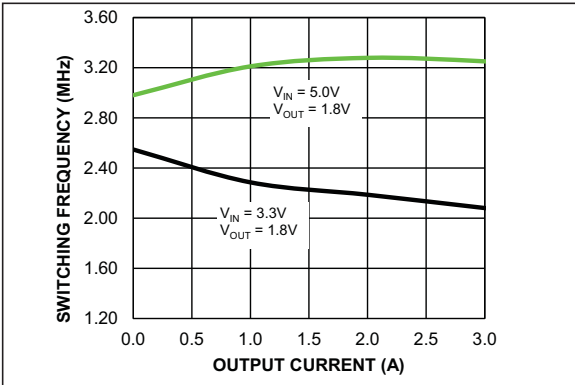


FIGURE 2-16: Switching Frequency vs. Output Current.

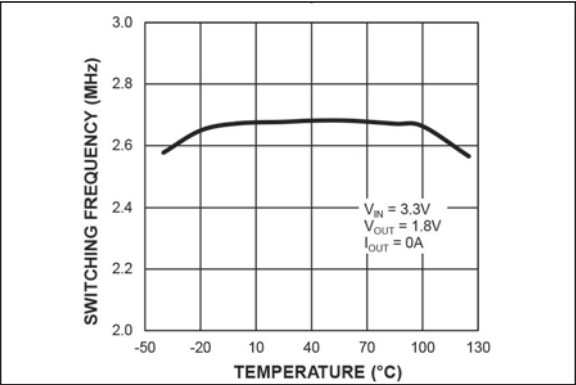


FIGURE 2-14: Switching Frequency vs. Temperature.

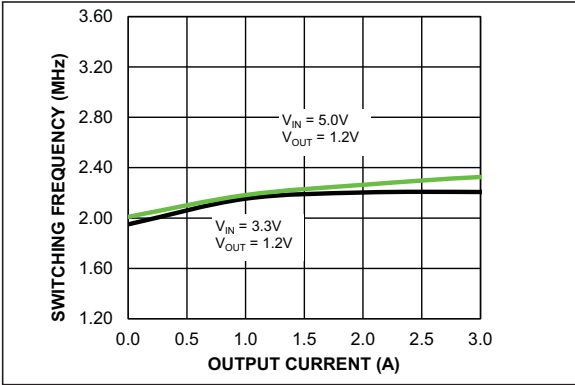


FIGURE 2-17: Switching Frequency vs. Output Current.

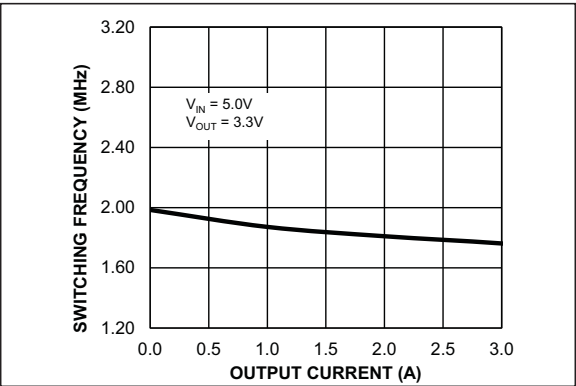


FIGURE 2-15: Switching Frequency vs. Output Current.

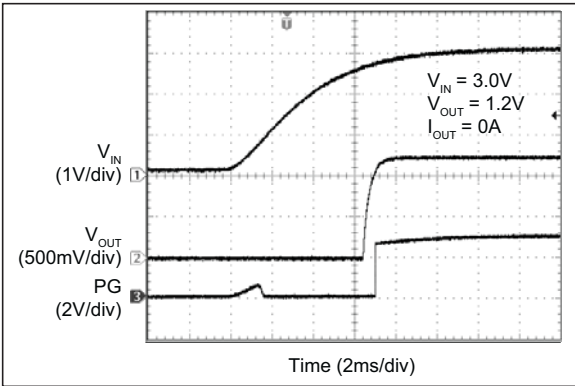
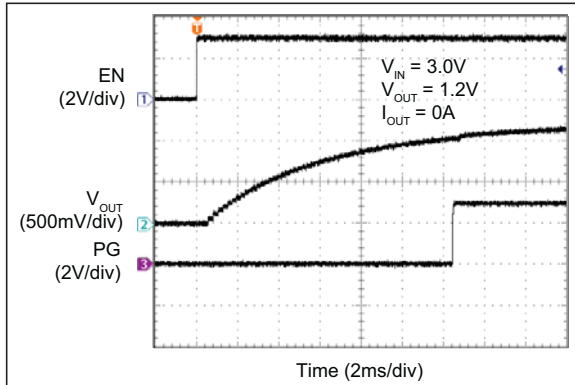
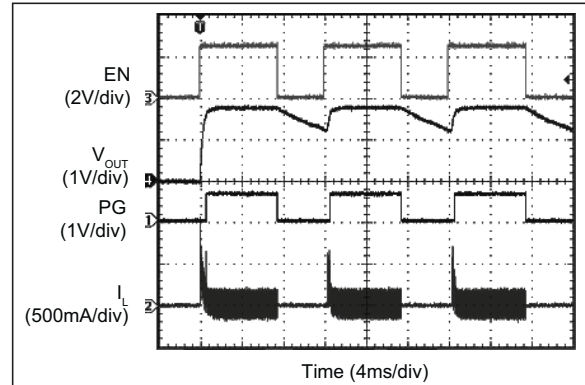


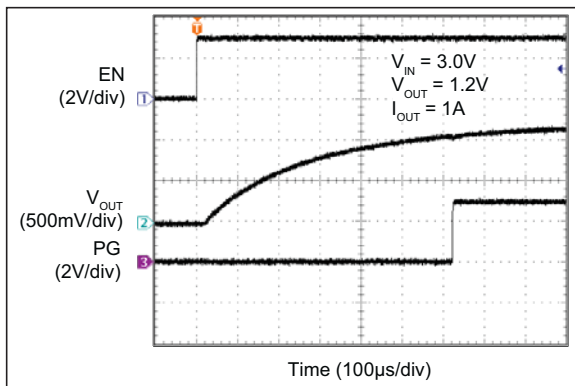
FIGURE 2-18:  $V_{IN}$  Soft Turn-On.



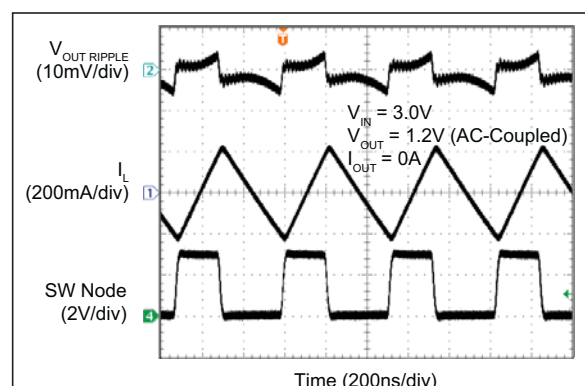
**FIGURE 2-19:** Enable Turn-On (No Load).



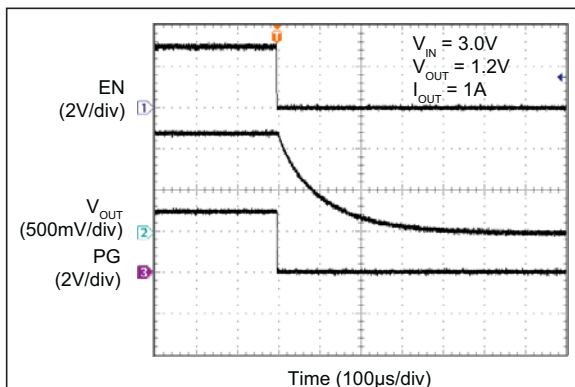
**FIGURE 2-22:** 1.4V Pre-Bias Start-Up (EN Rising).



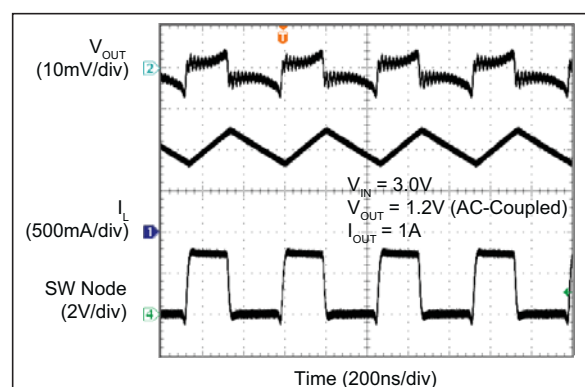
**FIGURE 2-20:** Enable Turn-On (1A Load).



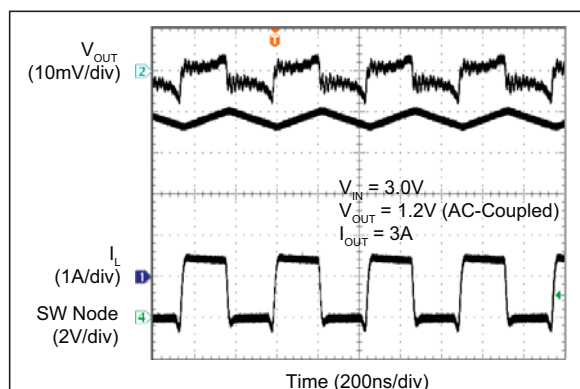
**FIGURE 2-23:** Switching Waveforms (I<sub>OUT</sub> = 0A).



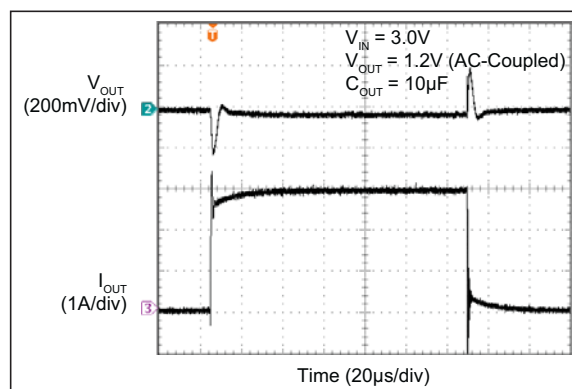
**FIGURE 2-21:** Enable Turn-Off (1A Load).



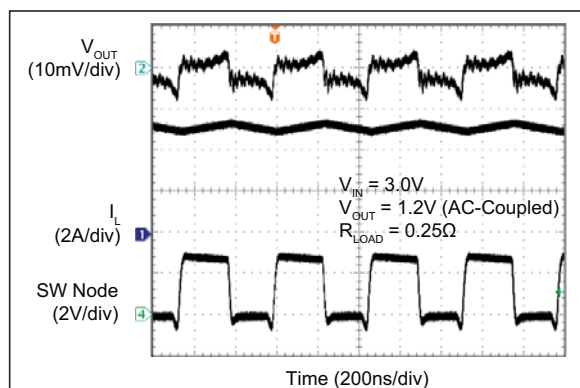
**FIGURE 2-24:** Switching Waveforms (I<sub>OUT</sub> = 1A).



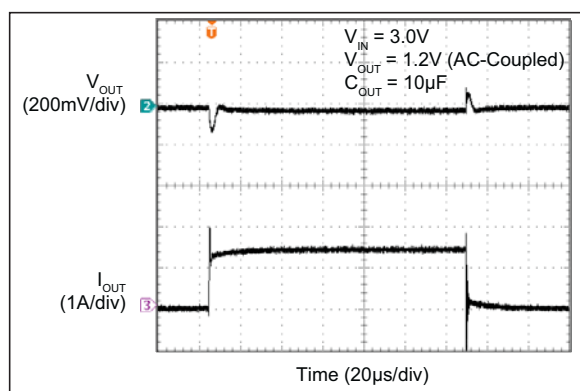
**FIGURE 2-25:** Switching Waveforms ( $I_{OUT} = 3A$ ).



**FIGURE 2-28:** Load Transient Response ( $I_{OUT} = 3A$ ).



**FIGURE 2-26:** Switching Waveforms (Current Limit).



**FIGURE 2-27:** Load Transient Response ( $I_{OUT} = 1.5A$ ).

### 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

**TABLE 3-1: PIN FUNCTION TABLE**

3X4 DFN	Symbol	Description
1, 2, EP	PGND	Power Ground.
3, 8	PVIN	Power input voltage: Connect a 10 $\mu$ F ceramic capacitor between PVIN and PGND for input decoupling. Pins 3 and 8 are internally connected inside the package.
4	AVIN	Analog input voltage: Connect a 1 $\mu$ F ceramic capacitor between AVIN and AGND to decouple the noise for the internal reference and error comparator.
5	AGND	Analog ground input: Connect to a quiet ground plane for best operation. Do not route power switching currents on the AGND net. Connect AGND and PGND nets together at a single point.
6	FB	Feedback (input): Connect an external divider between VOUT and AGND to program the output voltage.
7	PG	Power Good (output): Open-drain output. A pull-up resistor from this pin to a voltage source is required to detect an output power-is-good condition.
9	EN	Enable (input): Logic high enables operation of the regulator. Logic low will shut down the device. Do not leave floating.
10	SW	Switch (output): Internal power MOSFET output switches.

## 4.0 FUNCTIONAL DESCRIPTION

### 4.1 $PV_{IN}$

The power input ( $PV_{IN}$ ) pin provides power to the internal MOSFETs for the switch mode regulator section of the MIC4930. The input supply operating range is from 2.7V to 5.5V. A low-ESR ceramic capacitor of at least 10  $\mu$ F is required to bypass from  $PV_{IN}$  to (power) GND. See the [Application Information](#) section for further details.

### 4.2 $AV_{IN}$

The analog power input ( $AV_{IN}$ ) pin provides power to the internal control and analog supply circuitry. Careful layout should be considered to ensure that high-frequency switching noise caused by  $PV_{IN}$  is reduced before reaching  $AV_{IN}$ . Always place a 1  $\mu$ F minimum ceramic capacitor very close to the IC between the  $AV_{IN}$  and AGND pins. For additional high-frequency switching noise attenuation, RC filtering can be used ( $R = 10\Omega$ ).

### 4.3 EN

A logic high signal on the enable (EN) pin activates the output of the switch. A logic low on EN deactivates the output and reduces the supply current to a nominal 0.01  $\mu$ A. Do not leave this pin floating.

### 4.4 SW

The switch (SW) pin connects directly to one side of the inductor and provides the current path during switching cycles. The other end of the inductor is connected to the load and output capacitor. Due to the high speed switching on this pin, the switch node should be routed away from sensitive nodes whenever possible to avoid unwanted injection of noise.

### 4.5 PGND

The power ground (PGND) pin is the ground return terminal for the high current in the switching node SW. The current loop for the PGND should be as short as possible and kept separate from the AGND net whenever applicable.

### 4.6 PG

The power-is-good (PG) pin is an open-drain output that indicates logic high when the output voltage is typically above 88% of its steady-state voltage. A pull-up resistor of 10 k $\Omega$  or greater should be connected from PG to  $V_{OUT}$ , or to another voltage source less than or equal to the input voltage.

### 4.7 FB

To program the output voltage, an external resistive divider network is connected to this pin from the output voltage to AGND, as shown in the [Typical Application Circuit](#), and is compared to the internal 0.625V reference within the regulation loop. The formula in [Equation 4-1](#) is used to program the output voltage.

**EQUATION 4-1:**

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R1}{R2}\right)$$

**TABLE 4-1: RECOMMENDED FEEDBACK RESISTOR VALUES**

$V_{OUT}$	R1	R2
1.0V	120k	180k
1.2V	274k	294k
1.5V	316k	226k
1.8V	301k	160k
2.5V	316k	105k
3.3V	309k	71.5k

The feed-forward capacitor ( $C_F$  in the [Typical Application Circuit](#)) is typically in the range of 22 pF to 39 pF. The MIC4930 features an internal ripple injection network, whose current is injected into the FB node and integrated by  $C_F$ . Thus, the waveform at FB is approximately a triangular ripple. The size of  $C_F$  dictates the amount of ripple amplitude at the FB node. Smaller values of  $C_F$  yield higher FB ripple amplitudes and better stability, but also somewhat degrade line regulation and transient response.

## 4.8 Hyper Speed Control®

MIC4930 uses an ON- and OFF-time proprietary ripple-based control loop that features three different timers:

- Minimum ON Time
- Maximum ON Time
- Minimum OFF Time

When the required duty cycle is very low, the required OFF time is typically far from the minimum OFF time limit (about 176 ns typically). In this case, the MIC4930 operates by delivering a determined ON time at each switching cycle, depending on the input voltage. A new ON time is invoked by the error comparator when the FB voltage falls below the regulation threshold. In this mode, the MIC4930 operates as an adaptive constant-ON-time ripple controller with nearly constant switching frequency. Regulation takes place by controlling the valley of the FB ripple waveform.

When higher duty cycles are required, regulation can no longer be maintained by decreasing the OFF time below the minimum OFF time limit. When this limit is reached, the OFF time is no longer reduced, and the MIC4930 smoothly transitions to an ON-time modulation mode. In the ON-time modulation region, frequency reduces with the increase of the required ON-time / duty cycle, and regulation finally takes place on the peak of the FB ripple waveform.

Note that because of the shift of the regulation threshold between different modes, line regulation might suffer when the input voltage and/or duty cycle variations force the MIC4930 to switch from one regulation mode to the other. In applications where wide input voltage variations are expected, ensure that the line regulation is adequate for the intended application.

## 5.0 APPLICATION INFORMATION

The MIC4930 is a highly efficient, 3A synchronous buck regulator ideally suited for supplying processor core and I/O voltages from a 5V or 3.3V bus.

### 5.1 Input Capacitor

A 10  $\mu\text{F}$  ceramic capacitor or greater should be placed close to the  $\text{PV}_{\text{IN}}$  pin and PGND pin for bypassing. A X5R or X7R temperature rating is recommended for the input capacitor. Take into account C vs. bias effect in order to estimate the effective capacitance and the input ripple at the  $\text{V}_{\text{IN}}$  voltage.

### 5.2 Output Capacitor

The MIC4930 is designed for use with a 10  $\mu\text{F}$  or greater ceramic output capacitor. Increasing the output capacitance will lower output ripple and improve load transient response. A low equivalent series resistance (ESR) ceramic output capacitor is recommended based upon performance, size, and cost. Ceramic capacitors with X5R or X7R temperature ratings are recommended.

### 5.3 Inductor Selection

When selecting an inductor, it is important to consider the following factors:

- Inductance
- Rated current value
- Size requirements
- DC resistance (DCR)
- Core losses

The MIC4930 is designed for use with a 1  $\mu\text{H}$  to 2.2  $\mu\text{H}$  inductor. For faster transient response, a 1  $\mu\text{H}$  inductor will yield the best result. For lower output ripple, a 2.2  $\mu\text{H}$  inductor is recommended.

Inductor current ratings are generally given in two methods: permissible DC current, and saturation current. Permissible DC current can be rated for a 20°C to 40°C temperature rise. Saturation current can be rated for a 10% to 30% loss in inductance. Ensure that the nominal current of the application is well within the permissible DC current ratings of the inductor, also depending on the allowed temperature rise. Note that the inductor permissible DC current rating typically does not include inductor core losses. These are a very important contribution to the total inductor core loss and temperature increase in high-frequency DC-to-DC converters, since core losses increase with at least the square of the excitation frequency. For more accurate core loss estimation, it is recommended to refer to manufacturers' datasheets or websites.

When saturation current is specified, make sure that there is enough design margin, so that the peak current does not cause the inductor to enter saturation.

Also pay attention to the inductor saturation characteristic in current limit. The inductor should not heavily saturate even in current limit operation, otherwise the current might instantaneously run away and reach potentially destructive levels. Typically, ferrite-core inductors exhibit an abrupt saturation characteristic, while powdered-iron or composite inductors have a soft-saturation characteristic.

Peak current can be calculated by using [Equation 5-1](#).

#### EQUATION 5-1:

$$I_{PEAK} = \left[ I_{OUT} + V_{OUT} \times \left( \frac{1 - V_{OUT}/V_{IN}}{2 \times f \times L} \right) \right]$$

As shown by the calculation above, the peak inductor current is inversely proportional to the switching frequency and the inductance. The lower the switching frequency or inductance, the higher the peak current. As input voltage increases, the peak current also increases.

The size of the inductor depends on the requirements of the application. Refer to the typical application circuit and Bill of Materials for details.

DC resistance (DCR) is also important. While DCR is inversely proportional to size, DCR can represent a significant efficiency loss. Refer to the Efficiency Considerations subsection.

### 5.4 Efficiency Considerations

Efficiency is defined as the amount of useful output power, divided by the amount of power supplied. (See [Typical Performance Curves](#) section).

#### EQUATION 5-2:

$$\text{Efficiency}\% = \left( \frac{V_{OUT} \times I_{OUT}}{V_{IN} \times I_{IN}} \right) \times 100$$

There are two types of losses in switching converters; DC losses and switching losses. DC losses are simply the power dissipation of  $I^2R$ . Power is dissipated in the high side switch during the on cycle. Power loss is equal to the high side MOSFET  $R_{\text{DS(on)}}$  multiplied by the switch current squared. During the off cycle, the low side N-channel MOSFET conducts, also dissipating power. The device operating current also reduces efficiency. The product of the quiescent (operating) current and the supply voltage represents another DC loss. The current required driving the gates on and off at high frequency and the switching transitions make up the switching losses.

At the higher currents for which the MIC4930 is designed, efficiency loss is dominated by MOSFET  $R_{\text{DS(on)}}$  and inductor losses. Higher input supply voltages will increase the gate-to-source threshold on the internal MOSFETs, thereby reducing the internal

$R_{DS(on)}$ . This improves efficiency by reducing DC losses in the device. All but the inductor losses are inherent to the device. In that case, inductor selection becomes increasingly critical in efficiency calculations. As the inductors are reduced in size, the DC resistance (DCR) can become quite significant. The DCR losses can be calculated as in [Equation 5-3](#).

## EQUATION 5-3:

$$P_{DCR} = I_{OUT}^2 \times DCR$$

From that, the loss in efficiency due to inductor DCR and core losses ( $P_{CORE}$ ) can be calculated as in [Equation 5-4](#).

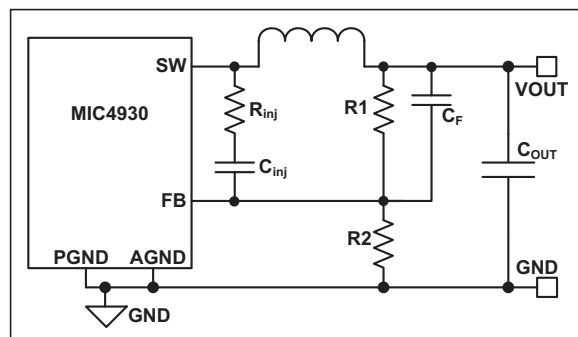
## EQUATION 5-4:

$$\text{Efficiency Loss (\%)} = \left[ 1 - \left( \frac{V_{OUT} \times I_{OUT}}{V_{OUT} \times I_{OUT} + P_{DCR} + P_{CORE}} \right) \right] \times 100$$

## 5.5 External Ripple Injection

The MIC4930 control loop is ripple-based, and relies on an internal ripple injection network to generate enough ripple amplitude at the FB pin when negligible output voltage ripple is present. The internal ripple injection network is typically sufficient when recommended R1-R2 and  $C_F$  values are used. The FB ripple amplitude should fall in the 20 mV to 100 mV range.

If significantly lower divider resistors and/or higher  $C_F$  values are used, the amount of internal ripple injection may not be sufficient for stable operation. In this case, external ripple injection is needed. This is accomplished by connecting a series  $R_{inj}$ - $C_{inj}$  circuit between the SW and the FB pins, as shown in



**FIGURE 5-1:** External Ripple Injection.

The injected ripple is:

## EQUATION 5-5:

$$\Delta V_{FB(PP)} = V_{IN} \times K_{div} \times D \times (1 - D) \times \frac{1}{f_{SW} \times \tau}$$

Where:

$V_{IN}$ =	Power stage input voltage
$D$ =	Duty cycle; $V_{OUT}/V_{IN}$
$f_{SW}$ =	Switching frequency
$T$ =	$(R1/R2/R_{inj}) \times C_F$

with  $K_{div}$  given by:

## EQUATION 5-6:

$$K_{div} = \frac{R1/R2}{R_{INJ} + R1/R2}$$

In [Equation 5-5](#) and [Equation 5-6](#), it is assumed that the time constant associated with  $C_F$  must be greater than the switching period.

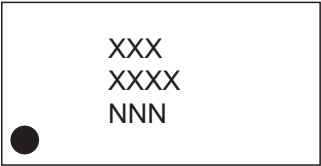
## EQUATION 5-7:

$$\frac{1}{f_{SW} \times \tau} = \frac{T}{\tau} \ll 1$$

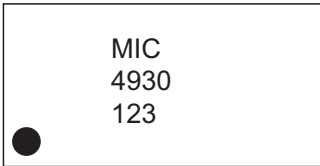
## 6.0 PACKAGING INFORMATION

### 6.1 Package Marking Information

10-Lead FDFN\*



Example



**Legend:**

XX...X	Product code or customer-specific information
Y	Year code (last digit of calendar year)
YY	Year code (last 2 digits of calendar year)
WW	Week code (week of January 1 is week '01')
NNN	Alphanumeric traceability code
(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
•, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).

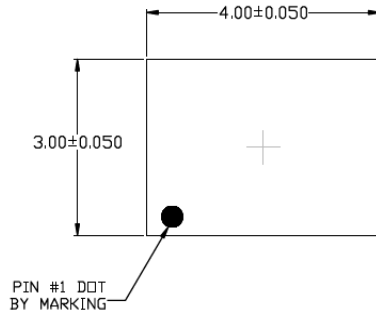
**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.  
  
Underbar ( \_ ) and/or Overbar ( ¯ ) symbol may not be to scale.

## 10 Lead DFN 4 mm × 3 mm Package (Flip Chip) Outline & Recommended Land Pattern

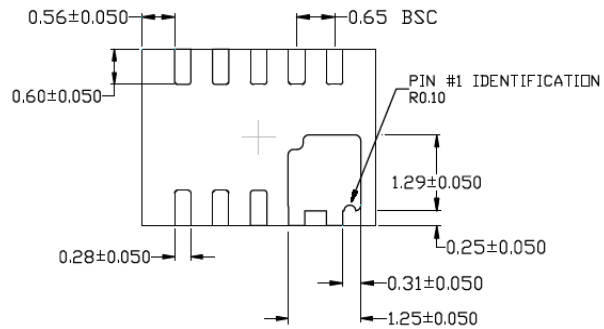
### TITLE

10 LEAD DFN 4x3mm PACKAGE (Flip Chip) OUTLINE & RECOMMENDED LAND PATTERN

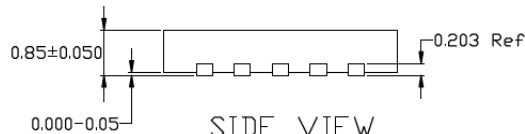
<b>DRAWING #</b>	FDFN43-10LD-PL-1	<b>UNIT</b>	MM
<b>Lead Frame</b>	Copper	<b>Lead Finish</b>	Matte Tin



**TOP VIEW**  
NOTE: 1, 2, 3



**BOTTOM VIEW**  
NOTE: 1, 2



**SIDE VIEW**  
NOTE: 1, 2

### NOTE:

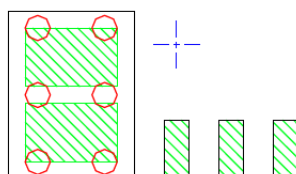
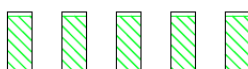
1. MAX PACKAGE WARPAGE IS 0.05MM
2. MAX ALLOWABLE BURR IS 0.076MM IN ALL DIRECTIONS
3. PIN #1 IS ON TOP WILL BE LASER MARKED
4. GREEN RECTANGLES (SHADED AREA) REPRESENT STENCIL OPENING ON EXPOSED AREA. SIZE IS 0.85X0.87 MM, 1.07 MM PITCH SPACING
5. RED CIRCLES REPRESENT THERMAL VIAS & SHOULD BE CONNECTED TO GND FOR MAX PERFORMANCE. 0.30 - 0.35 MM RECOMMENDED DIAMETER, 0.80MM PITCH SPACING

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

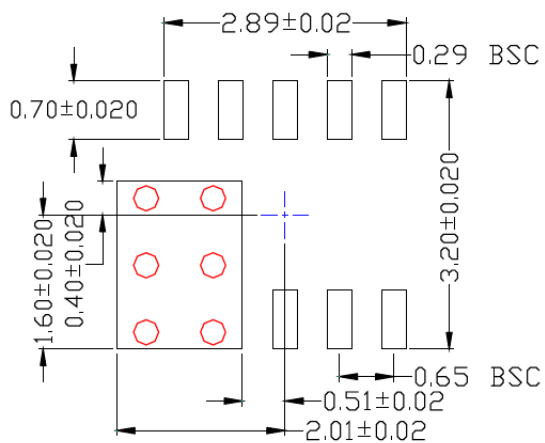
POD-Land Pattern drawing #FDFN43-10LD-PL-1

## RECOMMENDED LAND PATTERN

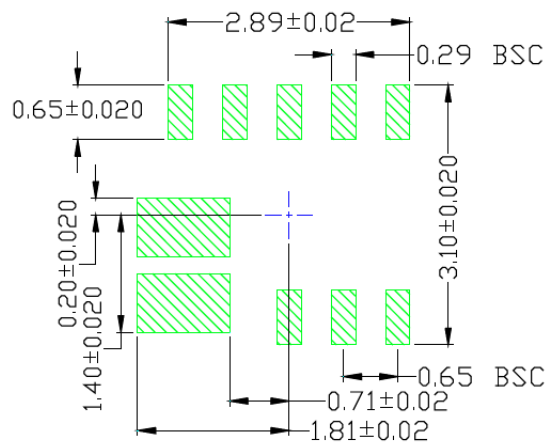
NOTE: 4, 5



STACKED-UP



EXPOSED METAL TRACE



SOLDER STENCIL OPENING

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>.

## APPENDIX A: REVISION HISTORY

### Revision A (November 2016)

- Converted Micrel document MIC4930 to Microchip data sheet template DS20005669A.
- Minor grammatical text changes throughout.

NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>			
Device	X	XX	
	Temperature Range	Package	
<b>Device:</b>	MIC4930:	Hyper Speed Control® 3A Buck Regulator	
<b>Temperature Range:</b>	Y	=	–40°C to +125°C
<b>Packages:</b>	FL	=	10-Pin 3 mm x 4 mm FQFN

**Examples:**

a) MIC4930YFL: Hyper Speed Control® 3A Buck Regulator, –40°C to +125°C Temperature Range, 10LD FQFN

**Note 1:** Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

NOTES:

---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

*Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELoQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.*

**QUALITY MANAGEMENT SYSTEM**  
**CERTIFIED BY DNV**  
**== ISO/TS 16949 ==**

### Trademarks

The Microchip name and logo, the Microchip logo, AnyRate, AVR, AVR logo, AVR Freaks, BeaconThings, BitCloud, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, Helder, JukeBlox, KEELoQ, KEELoQ logo, Klear, LANCheck, LINK MD, maxStylus, maxTouch, MediaLB, megaAVR, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, Prochip Designer, QTouch, RightTouch, SAM-BA, SpyNIC, SST, SST Logo, SuperFlash, tinyAVR, UNI/O, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

ClockWorks, The Embedded Control Solutions Company, EtherSynch, Hyper Speed Control, HyperLight Load, IntelliMOS, mTouch, Precision Edge, and Quiet-Wire are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, BodyCom, chipKIT, chipKIT logo, CodeGuard, CryptoAuthentication, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, EtherGREEN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, JitterBlocker, KlearNet, KlearNet logo, Mindi, MiWi, motorBench, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICKit, PICtail, PureSilicon, QMatrix, RightTouch logo, REAL ICE, Ripple Blocker, SAM-ICE, Serial Quad I/O, SMART-I.S., SQI, SuperSwitcher, SuperSwitcher II, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2016, Microchip Technology Incorporated, All Rights Reserved.  
ISBN: 978-1-5224-1100-0

## Worldwide Sales and Service

### AMERICAS

**Corporate Office**  
2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200  
Fax: 480-792-7277  
Technical Support:  
<http://www.microchip.com/support>  
Web Address:  
[www.microchip.com](http://www.microchip.com)

**Atlanta**  
Duluth, GA  
Tel: 678-957-9614  
Fax: 678-957-1455

**Austin, TX**  
Tel: 512-257-3370

**Boston**  
Westborough, MA  
Tel: 774-760-0087  
Fax: 774-760-0088

**Chicago**  
Itasca, IL  
Tel: 630-285-0071  
Fax: 630-285-0075

**Dallas**  
Addison, TX  
Tel: 972-818-7423  
Fax: 972-818-2924

**Detroit**  
Novi, MI  
Tel: 248-848-4000

**Houston, TX**  
Tel: 281-894-5983

**Indianapolis**  
Noblesville, IN  
Tel: 317-773-8323  
Fax: 317-773-5453  
Tel: 317-536-2380

**Los Angeles**  
Mission Viejo, CA  
Tel: 949-462-9523  
Fax: 949-462-9608  
Tel: 951-273-7800

**Raleigh, NC**  
Tel: 919-844-7510

**New York, NY**  
Tel: 631-435-6000

**San Jose, CA**  
Tel: 408-735-9110  
Tel: 408-436-4270

**Canada - Toronto**  
Tel: 905-695-1980  
Fax: 905-695-2078

### ASIA/PACIFIC

**Asia Pacific Office**  
Suites 3707-14, 37th Floor  
Tower 6, The Gateway  
Harbour City, Kowloon

**Hong Kong**  
Tel: 852-2943-5100  
Fax: 852-2401-3431

**Australia - Sydney**  
Tel: 61-2-9868-6733  
Fax: 61-2-9868-6755

**China - Beijing**  
Tel: 86-10-8569-7000  
Fax: 86-10-8528-2104

**China - Chengdu**  
Tel: 86-28-8665-5511  
Fax: 86-28-8665-7889

**China - Chongqing**  
Tel: 86-23-8980-9588  
Fax: 86-23-8980-9500

**China - Dongguan**  
Tel: 86-769-8702-9880

**China - Guangzhou**  
Tel: 86-20-8755-8029

**China - Hangzhou**  
Tel: 86-571-8792-8115  
Fax: 86-571-8792-8116

**China - Hong Kong SAR**  
Tel: 852-2943-5100  
Fax: 852-2401-3431

**China - Nanjing**  
Tel: 86-25-8473-2460  
Fax: 86-25-8473-2470

**China - Qingdao**  
Tel: 86-532-8502-7355  
Fax: 86-532-8502-7205

**China - Shanghai**  
Tel: 86-21-3326-8000  
Fax: 86-21-3326-8021

**China - Shenyang**  
Tel: 86-24-2334-2829  
Fax: 86-24-2334-2393

**China - Shenzhen**  
Tel: 86-755-8864-2200  
Fax: 86-755-8203-1760

**China - Wuhan**  
Tel: 86-27-5980-5300  
Fax: 86-27-5980-5118

**China - Xian**  
Tel: 86-29-8833-7252  
Fax: 86-29-8833-7256

### ASIA/PACIFIC

**China - Xiamen**  
Tel: 86-592-2388138  
Fax: 86-592-2388130

**China - Zhuhai**  
Tel: 86-756-3210040  
Fax: 86-756-3210049

**India - Bangalore**  
Tel: 91-80-3090-4444  
Fax: 91-80-3090-4123

**India - New Delhi**  
Tel: 91-11-4160-8631  
Fax: 91-11-4160-8632

**India - Pune**  
Tel: 91-20-3019-1500

**Japan - Osaka**  
Tel: 81-6-6152-7160  
Fax: 81-6-6152-9310

**Japan - Tokyo**  
Tel: 81-3-6880-3770  
Fax: 81-3-6880-3771

**Korea - Daegu**  
Tel: 82-53-744-4301  
Fax: 82-53-744-4302

**Korea - Seoul**  
Tel: 82-2-554-7200  
Fax: 82-2-558-5932 or  
82-2-558-5934

**Malaysia - Kuala Lumpur**  
Tel: 60-3-6201-9857  
Fax: 60-3-6201-9859

**Malaysia - Penang**  
Tel: 60-4-227-8870  
Fax: 60-4-227-4068

**Philippines - Manila**  
Tel: 63-2-634-9065  
Fax: 63-2-634-9069

**Singapore**  
Tel: 65-6334-8870  
Fax: 65-6334-8850

**Taiwan - Hsin Chu**  
Tel: 886-3-5778-366  
Fax: 886-3-5770-955

**Taiwan - Kaohsiung**  
Tel: 886-7-213-7830

**Taiwan - Taipei**  
Tel: 886-2-2508-8600  
Fax: 886-2-2508-0102

**Thailand - Bangkok**  
Tel: 66-2-694-1351  
Fax: 66-2-694-1350

### EUROPE

**Austria - Wels**  
Tel: 43-7242-2244-39  
Fax: 43-7242-2244-393

**Denmark - Copenhagen**  
Tel: 45-4450-2828  
Fax: 45-4485-2829

**Finland - Espoo**  
Tel: 358-9-4520-820

**France - Paris**  
Tel: 33-1-69-53-63-20  
Fax: 33-1-69-30-90-79

**France - Saint Cloud**  
Tel: 33-1-30-60-70-00

**Germany - Garching**  
Tel: 49-8931-9700

**Germany - Haan**  
Tel: 49-2129-3766400

**Germany - Heilbronn**  
Tel: 49-7131-67-3636

**Germany - Karlsruhe**  
Tel: 49-721-625370

**Germany - Munich**  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

**Germany - Rosenheim**  
Tel: 49-8031-354-560

**Israel - Ra'anana**  
Tel: 972-9-744-7705

**Italy - Milan**  
Tel: 39-0331-742611  
Fax: 39-0331-466781

**Italy - Padova**  
Tel: 39-049-7625286

**Netherlands - Drunen**  
Tel: 31-416-690399  
Fax: 31-416-690340

**Norway - Trondheim**  
Tel: 47-7289-7561

**Poland - Warsaw**  
Tel: 48-22-3325737

**Romania - Bucharest**  
Tel: 40-21-407-87-50

**Spain - Madrid**  
Tel: 34-91-708-08-90  
Fax: 34-91-708-08-91

**Sweden - Gothenberg**  
Tel: 46-31-704-60-40

**Sweden - Stockholm**  
Tel: 46-8-5090-4654

**UK - Wokingham**  
Tel: 44-118-921-5800  
Fax: 44-118-921-5820

# Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Microchip:](#)

[MIC4930YFL TR](#) [MIC4930YFL-TR](#)